

ABSTRACT OF THE DISCLOSURE

A circuit board assembly comprising a laminate substrate and a surface mount device having a CTE less than that of the laminate substrate and attached with at least one solder joint to a first surface of the laminate substrate. The assembly further includes a localized stiffener attached to a second surface of the laminate substrate so as to be directly opposite the circuit device. The localized stiffener is formed of a material and is shaped so that, when attached to the laminate substrate, the stiffener is capable of increasing the thermal cycle fatigue life of the one or more solder joints that attach the device to the substrate.